

# High Speed Die Sorter



## FEATURES

Dual Pick and Place

Complete Surface Inspection

Vision Aided Correction  
before Taping

Tool Less Conversion

Reel to Reel and  
Re-construction Capability

## CAERUS C320

Your Sort Solution



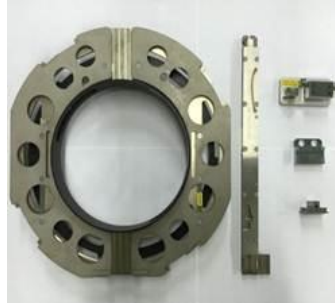
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# Features



## Performance

- Dual Pick and Place
- Programmable Die Pickup Force
- Thin Die Handling Up To 60µm



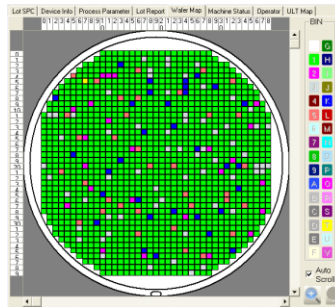
## Ease of Use

- Tool Less Design for Quick Conversion
- Easy Maintenance
- Versatile Output Options



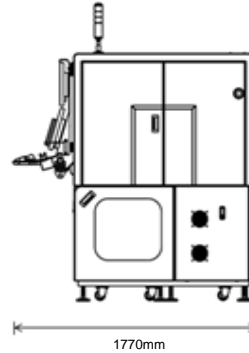
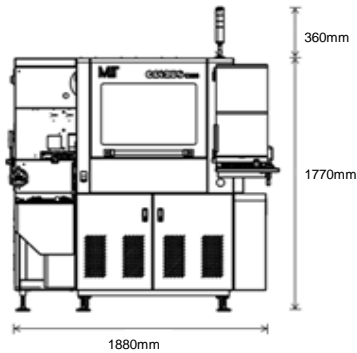
## Vision

- Implied 3D, Side Wall Inspection
- Surface Defects Up To 10µm
- Vision Aided Correction Before Taping



## Software

- Full Wafer Mapping Capability
- Unit Level Tracking, Multi Die Capability
- SECSGEM, RMS



### Package Type

Die Level (Flip Chip)

### Performance

Up to 20,000 units per hour

### System Control

PC Based - Window XP Platform

### Wafer Input Size

200mm(8") and 300mm(12")

### Taping Placement Accuracy

±25µm

### Facilities Requirement

Electrical: 230VAC, single phase ±5% at 50/60Hz  
Compressed Air: Min 5 bars

### Device Specifications

0.2 x 0.2mm to 8.0 x 8.0mm  
0.1mm to 1.2mm (thickness)

### Machine Options

- Die Side Wall Inspection down to <10µm detection
- After Post Seal Inspection
- Wafer Reconstruction
- Reel to Reel

### Footprint

Dimension: 1880mm x 1770mm  
Weight: 2,800kg

### Carrier Tape

Width: 8mm, 12mm, 16mm

Final machine performance is subjected to user specific process